

EAST - [10749890.wsp:1]

File View Edit Tools Window Help

Search:

DBs:

Default operator: ☒ Highlight all items in list

an isotropic near conductive near adhesive and (particle\$1) and (wafer\$1 substrate\$1)

☐ Drafts
☐ Pending
☒ Active
☐ Failed
☐ Saved
☐ Favorites
☐ Tagged (0)
☐ UDC
☐ Queue
☐ Trash

☐ L1: (8591) an isotropic and (wafer substrate) and contact and particle\$1
☐ L2: (3362) an isotropic and (wafer substrate) and contact and particle\$1 and adhesive
☐ L4: (37) an isotropic and (wafer substrate) and raised near contact and particle\$1
☐ L3: (27) an isotropic and (wafer substrate) and raised near contact and particle\$1 and adhesive
☐ L5: (0) an isotropic and (wafer substrate) and first near raised near contact and particle\$1 and a...
☐ L6: (27) an isotropic and (wafer substrate) and raised near contact and particle\$1 and adhesive
☐ L7: (2) an isotropic and first near raised near contact
☐ L8: (3362) an isotropic and (wafer substrate) and contact and particle\$1 and adhesive
☐ L9: (32) 8 and (trapped near particle\$1)
☐ L10: (2155) an isotropic and (first near wafer first near substrate) and contact and particle\$1
☐ L11: (1120) an isotropic near conductive and (first near wafer first near substrate) and contact
☐ L12: (555) an isotropic near conductive and (first near wafer first near substrate) and contact an...
☐ L13: (452) an isotropic near conductive and (first near wafer first near substrate) and contact an...
☐ L14: (7) an isotropic near conductive and (first near wafer first near substrate) and raised near...
☐ L15: (10) an isotropic near conductive and (first near wafer first near substrate) and raised near...
☐ L16: (13) an isotropic near conductive near adhesive and (stack\$3 near wafer) and contact
☐ L17: (13) an isotropic near conductive near adhesive and (stack\$3 near wafer)
☐ L18: (976) an isotropic near conductive near adhesive and (substrate wafer)
☐ L19: (2519) an isotropic near conductive near adhesive or (anisotropic near conductive near film...
☐ L20: (2294) an isotropic near conductive near adhesive or (anisotropic near conductive near film...
☐ L21: (735) an isotropic near conductive near adhesive and (particle\$1)
☐ L22: (546) an isotropic near conductive near adhesive and (particle\$1) and (wafer\$1 substrate\$1)

	U	I	Document ID	Issue Date	Pages	Title	Current OR	Current XRef	
283	<input type="checkbox"/>	<input type="checkbox"/>	US 6534710 B2	20030318	30	Packaging and interconnection of contact structure	174/52.1	257/737; 257/738; 261/736;	
284	<input type="checkbox"/>	<input type="checkbox"/>	US 6528343 B1	20030304	27	Semiconductor device its manufacturing method and electronic device	438/106	257/734; 257/758; 257/771;	
285	<input type="checkbox"/>	<input type="checkbox"/>	US 6525716 B1	20030225	39	Flexible circuit board and liquid crystal display device incorporating the same	345/206	345/103; 349/150	
286	<input type="checkbox"/>	<input type="checkbox"/>	US 6522378 B1	20030218	14	Liquid crystal display and manufacture therefore	349/139	349/152	
287	<input type="checkbox"/>	<input type="checkbox"/>	US 6519021 B1	20030211	21	Wiring board for connection of electro-optical panel, electro-optical device and electronic apparatus	349/152	349/151	
288	<input type="checkbox"/>	<input type="checkbox"/>	US 6518557 B1	20030211	31	Two-dimensional image detector, active-matrix substrate, and display device	250/208.1	250/214.1; 257/443; 257/676;	
289	<input type="checkbox"/>	<input type="checkbox"/>	US 6518097 B1	20030211	9	Method for fabricating wafer-level flip chip package using pre-coated anisotropic conductive adhesive	438/119	257/E21.508; 257/E21.514; 418/108;	
290	<input type="checkbox"/>	<input type="checkbox"/>	US 6514796 B2	20030204	13	Method for mounting a thin semiconductor device	438/118	438/119; 438/458; 438/459;	
291	<input type="checkbox"/>	<input type="checkbox"/>	US 6514560 B2	20030204	6	Method for manufacturing conductive adhesive for high frequency flip chip package applications	427/96.1	257/E21.514; 427/201; 427/207.1;	
292	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 6507095 B1	20030114	35	Wiring board, connected board and semiconductor device, method of manufacture thereof, circuit board, and electronic instrument	257/676	257/668; 257/690; 257/691;	
293	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 6506980 B2	20030114	16	Semiconductor device and tape carrier, and method of manufacturing the same, circuit board, electronic instrument, and tape carrier manufacture	174/261	174/255; 174/260; 257/668;	